

## AMD Raphael(7000 series)

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### **Outline**

- General uses
- **■** Product timeline
- **■** System description
- **■** Technology analysis
- **Industry analysis**
- Applications
- Future
- reference



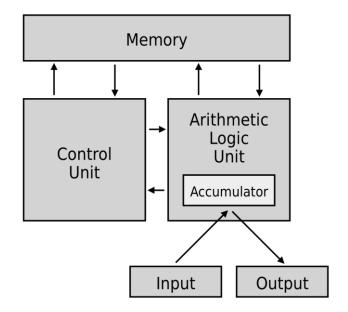


## **General uses**





### >CPU function



1. Retrieve the next instruction from memory (as indicated by the program counter) and then increment the program counter.

2. Decode the bit pattern in the instruction register.

Execute

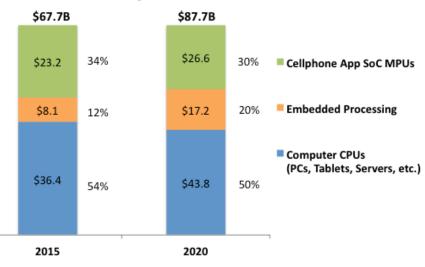
3. Perform the action required by the

instruction in the instruction register.



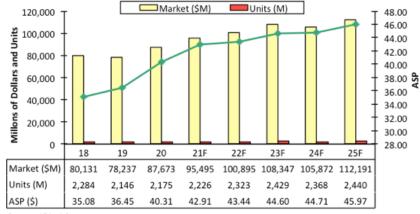


#### Shift in Microprocessor Sales, \$B



Source: IC Insights

#### **Total Microprocessor Market History and Forecast**



Source: IC Insights





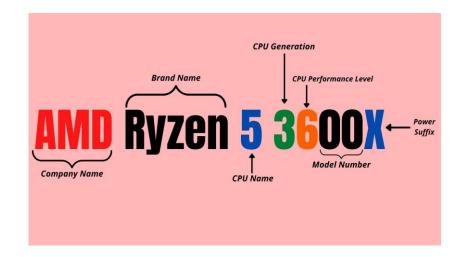
#### Ryzen Raphael (7000 series CPUs)

Ryzen 5 7600X

Ryzen 7 7700X

Ryzen 9 7900X

Ryzen 9 7950X



Ryzen 3 — Up to 4-core processors.

Ryzen 5 — Up to 6-core processors.

Ryzen 7 — Up to 8-core processors.

Ryzen 9 — Up to 16-core processors.

Ryzen Threadripper — Up to 64-core processors.

Ryzen 3 1xxx —1000 series CPUs

Ryzen 3 1xxxX —having high clock speed, power, consumption, and speed





## **Product timeline**



## **►AMD** product timeline(to 4th generation)

naced(1st generation)					High-end desktop(HED1)			
	Summit Ridge (1000 series	CPUs)			Ryzen Threadripper 2920X		Renoir (4000 series CPUs)	
		Fabrication process: Glo	palFoundries 14		Ryzen Threadripper 2950X		, , , , , , , , , , , , , , , , , , , ,	Fabrication process: TSMC 7 nm FinFET
		•			Ryzen Threadripper 2970W	X		Based on the Ryzen 4000G series APUs with
	Entry-level				Ryzen Threadripper 2990W			•
	,	Rvzen 3 1200		Picasso (3000 series APUs)	,		Ryzen 3	
		Ryzen 3 PRO 1200		,	Fabrication process:		,	Ryzen 3 4100
		Ryzen 3 PRO 1300	GlobalFoundries 12 nm		, , , , , , , , , , , , , , , , , , , ,		Ryzen 5	1,72011 5 1200
		Ryzen 3 1300X	0.000.00.00.00.00		Includes integrated GCN 5	th	.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	Ryzen 5 4500
	Mainstream	Nyzen s isoox	generation GPU			•••	Renoir (4000 series APUs)	1,720113 1300
	Wallscream	Ryzen 5 1400	generation of o		Ryzen 3 Pro 3200GE		Renon (4000 series Ar 03)	Fabrication process: TSMC 7 nm FinFET
		Ryzen 5 PRO 1500			Ryzen 3 3200G			Includes integrated GCN 5th generation GP
		Ryzen 5 1500X			Ryzen 3 Pro 3200G			Ryzen 3 4300GE
Ryzen 5 1600		NyZeli S 1500X			Ryzen 5 Pro 3350GE			Ryzen 3 4300G
Ryzen 5 PRO					Ryzen 5 Pro 3350GE			Ryzen 5 4600GE
Ryzen 5 1600					Ryzen 5 Pro 3400GE			Ryzen 5 4600G
11,72011 3 1000	Performance				Ryzen 5 3400G			Ryzen 7 4700GE
	renormance	Ryzen 7 1700			Ryzen 5 Pro 3400G			Ryzen 7 4700GE
		Ryzen 7 PRO 1700			Kyzell 3 Fl0 34000	Zen 3 based(4 <sup>th</sup> generation)		Kyzell 7 4700G
		Ryzen 7 1700X	Zen 2 based(3 <sup>rd</sup> generation)			Zeii 3 baseu(4 generation)	Vermeer and Chagall (5000	corios CRUs)
		Ryzen 7 1800X	zen z based(s. generation)	Matisse and Castle Peak (30	200 series CRUs)		vermeer and Chagaii (5000	Fabrication process: TSMC 7 nm FinFET
	High and daskton/HEDT\	Ryzell / 1800X		Matisse and Castle Peak (50		7		
	High-end desktop(HEDT)	D Th dain 4000	V FILEET		Fabrication process: TSMC	,		Vermeer (desktop), Chagall (Threadripper)
		Ryzen Threadripper 1900						The Ryzen 5 5500 is a Cezanne APU with its
		Ryzen Threadripper 1920			Matisse (desktop), Castle	integrated GPU disabled		
	D Did (2000i A	Ryzen Threadripper 1950	x Peak (Inreadripper)	Enter Inval			Mainstream	D
	Raven Ridge (2000 series A		I= 11 44	Entry-level	D 0.0400			Ryzen 5 5500
		Fabrication process: Glo	palFoundries 14		Ryzen 3 3100			Ryzen 5 5600
					Ryzen 3 3300X			Ryzen 5 5600X
		Includes integrated GCN	5th generation	Mainstream	B 5.0500		Performance	B 7.5300V
U					Ryzen 5 3500			Ryzen 7 5700X
		Ryzen 3 2200GE			Ryzen 5 3500X			Ryzen 7 5800
		Ryzen 3 PRO 2200GE			Ryzen 5 3600			Ryzen 7 5800X
		Ryzen 3 2200G			Ryzen 5 Pro 3600			Ryzen 7 5800X3D
		Ryzen 3 PRO 2200G			Ryzen 5 3600X		Enthusiast	
		Ryzen 5 2400GE			Ryzen 5 3600XT			Ryzen 9 5900
Ryzen 5 PRO				Performance				Ryzen 9 5900X
Ryzen 5 2400					Ryzen 7 Pro 3700			Ryzen 9 5950X
Ryzen 5 PRO	2400G				Ryzen 7 3700X		High-end desktop/Workstati	
+ based(2 <sup>nd</sup> generation)					Ryzen 7 3800X			Ryzen Threadripper PRO 5945WX
	Pinnacle Ridge (2000 series				Ryzen 7 3800XT			Ryzen Threadripper PRO 5955WX
		Fabrication process: Glo	palFoundries 12	Enthusiast				Ryzen Threadripper PRO 5965WX
					Ryzen 9 3900			Ryzen Threadripper PRO 5975WX
	Entry-level				Ryzen 9 Pro 3900			Ryzen Threadripper PRO 5995WX
		Ryzen 3 1200(AF)			Ryzen 9 3900X		Cezanne (5000 series APUs)	
		Ryzen 3 2300X			Ryzen 9 3900XT			Fabrication process: TSMC 7 nm FinFET
	Mainstream				Ryzen 9 3950X			Includes integrated GCN 5th generation GPL
		Ryzen 5 2500X		High-End Desktop (HEDT)				Ryzen 3 5300GE
		Ryzen 5 2600E			Ryzen Threadripper 3960X			Ryzen 3 5300G
		Ryzen 5 1600(AF)			Ryzen Threadripper 3970X			Ryzen 5 5600GE
		Ryzen 5 2600			Ryzen Threadripper 3990X			Ryzen 5 5600G
		Ryzen 5 2600X		Workstation				Ryzen 7 5700GE
	Performance				Ryzen Threadripper Pro			Ryzen 7 5700G
		Ryzen 7 2700E	3945WX					
		Ryzen 7 2700			Ryzen Threadripper Pro			
		Ryzen 7 PRO 2700	3955WX					
		Ryzen 7 PRO 2700X			Ryzen Threadripper Pro			
		Ryzen 7 2700X	3975WX		**			
		•			Ryzen Threadripper Pro			
			3995WX					



### **≻AMD** product timeline

Zen based(1st generation)

Summit Ridge (1000 series CPUs)

Fabrication process: GlobalFoundries 14 nm

Raven Ridge (2000 series APUs)

Fabrication process: GlobalFoundries 14 nm

Includes integrated GCN 5th generation GPU

Zen 3 based(4<sup>th</sup> generation)

**FinFET** 

Vermeer and Chagall (5000 series CPUs)

Fabrication process: TSMC 7 nm FinFET Vermeer (desktop), Chagall (Threadripper)

The Ryzen 5 5500 is a Cezanne APU with its integrated GPU

Fabrication process: TSMC 5 nm

**Includes integrated RDNA2 GPU** 

disabled

Cezanne (5000 series APUs)

Fabrication process: TSMC 7 nm FinFET Includes integrated GCN 5th generation GPU

Zen+ based(2<sup>nd</sup> generation)

Pinnacle Ridge (2000 series CPUs)

Fabrication process: GlobalFoundries 12 nm

Picasso (3000 series APUs)

Fabrication process: GlobalFoundries 12 nm **Includes integrated GCN 5th generation GPU** 

Zen 4 based (5th generation)

Raphael (7000 series CPUs)

Zen 2 based(3<sup>rd</sup> generation)

disabled

Matisse and Castle Peak (3000 series CPUs)

Fabrication process: TSMC 7 nm FinFET

Matisse (desktop), Castle Peak (Threadripper)

Renoir (4000 series CPUs)

Fabrication process: TSMC 7 nm FinFET

Based on the Ryzen 4000G series APUs with the integrated GPU

Ryzen 5

Ryzen 7

Ryzen 5 7600X

Renoir (4000 series APUs)

Fabrication process: TSMC 7 nm FinFET

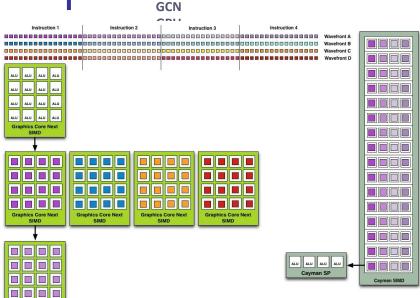
Ryzen 9 Includes integrated GCN 5th generation GPU

Ryzen 7 7700X

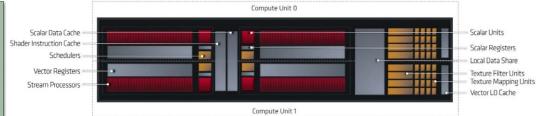
Ryzen 9 7900X Ryzen 9 7950X



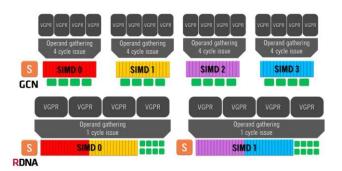




#### **RDNA2 GPU**



- ✓ two CUs working in tandem with shared local data.
- ✓ The RDNA SIMDs consist of 32 shaders or ALUs, twice that of GCN. There are two SIMDs per CU and four in a Dual Compute Unit.



64 wavefronts or work-items (and ALUs/cores) per Compute Unit.

Graphics Core Next SIMD

✓ divided into four SIMDs (Single Instruction On Multiple Data Types), each packing 16 ALUs (SP)

This arrangement allows the execution of one whole wavefront in one clock cycle



Product	time	line

晶粒種類	主要功能	製程技術	面積
CCD (Core Complex Die)	8個Zen3核心 · 32MB L3快取	台積電7nm	84.4
SIOD (Server I/O Die)	8通道記憶體控制器·I/O界面	GF 12nm	416
CIOD (Client I/O Die)	2通道記憶體控制器·I/O界面	GF 12nm	125
"Renoir" APU	8個Zen2核心(2個四核心CCX)・8個 Vega CU繪圖核心・8MB L3快取・2通道 記憶體控制器・各式各樣的I/O界面	台積電7nm	149

#### **CPU Mark Rating** As of 23rd of October 2022 - Higher results represent better performance AMD Ryzen 3 1300X 6,959 AMD Ryzen 7 5800X 28,128 zen 9 5950X 45,843 zen 7 7700X 36,443

Passh	dark	Software	© 2008-20	

	Processing power(GFLO PS)	-	-	-	563	563	563	AMD Ryze	en 9 5950X en 7 7700X en 9 7950X Software © 2008-
Socket		AM4	AM4	AM4	AM5	AM5	AM5	T dualities to	
PCIe lanes		24 (20+4) PCIe 3.0	24 (20+4) PCIe 4.0	24(20+4) PCle 4.0	28 (24+4) PCIe 5.0	28 (24+4) PCIe 5.0	28 (24+4 PCle 5.0	.)	
Memory suppo	ort	DDR4-2667 dual-channel	DDR4-3200 dual-channel	DDR4-3200 dual-channel	DDR5-5200 dual- channel	DDR5-5200 dual- channel	DDR5-52 dual- channel	.00	
TDP		65 W	105 W	105 W	105 W	105 W	170 W		

1000 series

2017/07/27

GloFo 14LP

Ryzen 3

1300X

US\$129

1×CCD

4 (4)

2×2

3.5/3.7

64 KB/2

MB/8 MB

Cores(thread

Core config

Clock rate

Cache

CUs

Boost

L1/L2/L3

Architecture

Clock rate

(GHz) Base/

(GHz) Base/ Boost

s)

Model

CPU

GPU

Release date and price

5000 series

2020/11/05

Ryzen 7

5800X

US\$449

TSMC N7

1×CCD

1×I/OD

8 (16)

1×8

3.8/4.7

512 KB/4

MB/32 MB

5000 series

2020/11/05

Ryzen 9

5950X

US\$799

TSMC N7

2×CCD

1xI/OD

16 (32)

3.4/4.9

1MB/8MB/6

2x8

4MB

7000 series

2022/09/27

Ryzen 5

7600X

US\$299

TSMC N5

1xCCD

1xI/OD

6 (12)

1×6

4.7/5.3

384 KB/6

RDNA 2

0.4/2.2

2

MB/32 MB

7000 series

2022/09/27

Ryzen 7

7700X

US\$399

TSMC N5

1xCCD

1×I/OD

8 (16)

1×8

4.5/5.4

512 KB/8

RDNA 2

0.4/2.2

2

MB/32 MB

7000 series

2022/09/27

Ryzen 9

7950X

US\$699

TSMC N5

2×CCD

1xI/OD

16 (32)

4.5/5.7

1 MB/16

RDNA 2

0.4/2.2

2

MB/64 MB

2×8





# **System description**



#### System description

	CPU Mark Rating	
	As of 23rd of October 2022 - Higher results represent better performance	е
AMD Ryzen 5 7600X		28,599
AMD Ryzen 9 7950X		64,346
Intel Core i5-13600K		38,084
Intel Core i9-13900K		58,261

PassMark Software © 2008-2022

(	intel

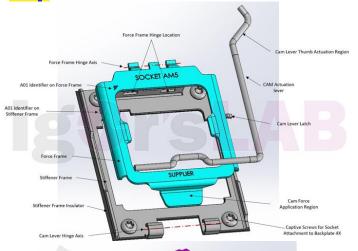
Model		Core i5 13600K	Core i7 13700K	Core i9 13900K	Ryzen 5 7600X	Ryzen 7 7700X	Ryzen 9 7950X
Release date and price		2022/09/27 US\$319	2022/09/27 US\$409	2022/09/27 US\$589	2022/09/27 US\$299	2022/09/27 US\$399	2022/09/27 US\$699
Fab		Intel 7	Intel 7	Intel 7	TSMC N5	TSMC N5	TSMC N5
Chiplets		-	-	-	1×CCD 1×I/OD	1×CCD 1×I/OD	2×CCD 1×I/OD
СРИ	Cores(threads)	14 (20)	16 (24)	24 (32)	6 (12)	8 (16)	16 (32)
	Core config	-	-	-	1×6	1×8	2×8
	Clock rate (GHz) Base/ Boost	3.5/ 5.1	3.4/ 5.4	3.0/ 5.8	4.7/ 5.3	4.5/ 5.4	4.5/ 5.7
	Cache L1/L2/L3	24 MB Intel® Smart Cache	30 MB Intel® Smart Cache	36 MB Intel® Smart Cache	384 KB/6 MB/32 MB	512 KB/8 MB/32 MB	1 MB/16 MB/64 MB
GPU	Architecture	Gen12 UHD 770	Gen12 UHD 770	Gen12 UHD 770	RDNA 2	RDNA 2	RDNA 2
	Execution Units /Compute Units	32	32	32	2	2	2
	Clock rate (GHz) Base/ Boost	0.3/1.55	0.3/1.6	0.3/1.65	0.4/2.2	0.4/2.2	0.4/2.2
	Processing power(GFLOPS)	-	-	-	563	563	563
Socket		LGA 1700	LGA 1700	LGA 1700	AM5	AM5	AM5
PCIe lanes		20 PCle 4.0	20 PCle 4.0	20 PCle 4.0	28 (24+4) PCle 5.0	28 (24+4) PCle 5.0	28 (24+4) PCle 5.0
Memory su	oport	DDR4-3200 /DDR5-5600	DDR4-3200 /DDR5-5600	DDR4-3200 /DDR5-5600	DDR5-5200 dual-channel	DDR5-5200 dual-channel	DDR5-5200 dual-channel
TDP		125 W/181 W (base/turbo)	125 W/253 W (base/turbo)	125 W/253 W (base/turbo)	105 W	105 W	170 W





A01 Identifier Triangular Mark

### **>AM5 V.S. AM4**

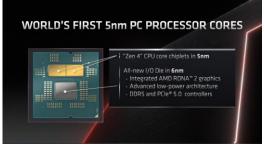


AMD expanded its maximum capacity from 142 watts to 230 watts allowing the newest Ryzen 7000 CPUs to have a maximum TDP of 170 watts

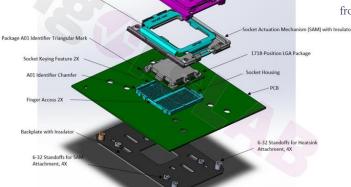


49% more powerful while utilizing the same amount of power, and it is 62% more efficient at the same performance

7000series have Integrated graphics RDNA 2



from the PGA(pin grid array) to the LGA(land grid array), 1,718 pins, AM5 is a significant upgrade over AM4's 1331





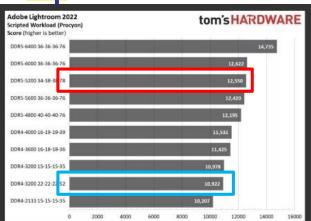




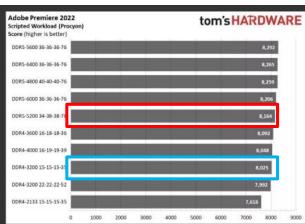


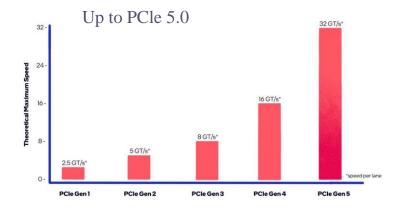
### **>AM5 V.S. AM4**

#### Up to DDR5 memory









#### AMD EXPO technology is available

gaming experience that is up to 11% quicker. Reduce lag time to 63 nanoseconds or less

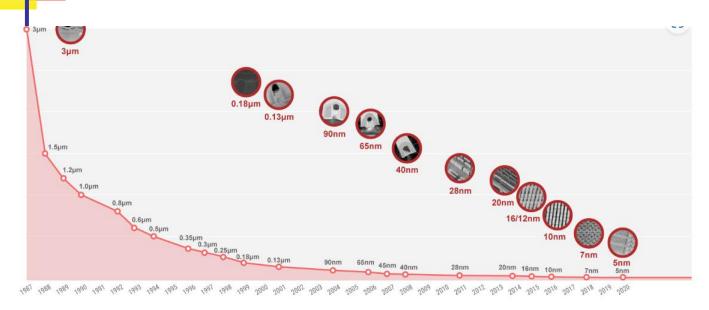


AM5 vs LGA 1700(intel)

AM5 has PCI-e Gen 5 storage LGA 1700 has flexible DDR4 or DDR5 platform set



# **►TSMC N5**



Process	N5	N7
Transistor density (MTr/mm2)	138.2	91.2–96.5
SRAM bit-cell size (μm2)	0.021	0.027
Transistor gate pitch (nm)	51	54
Interconnect pitch (nm)	28	40

Process	N5	Intel 7
Transistor density (MTr/mm2)	138.2	100.76–106.1
SRAM bit-cell size (μm2)	0.021	0.0312
Transistor gate pitch (nm)	51	54
Interconnect pitch (nm)	28	30

15% speed improvement or 30% lower power consumption



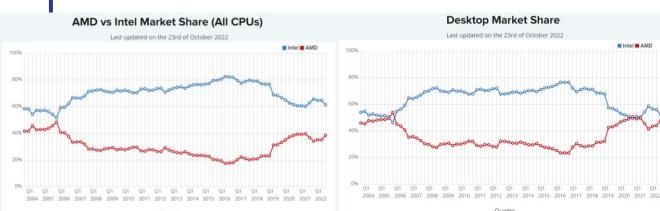


## **Industry analysis**

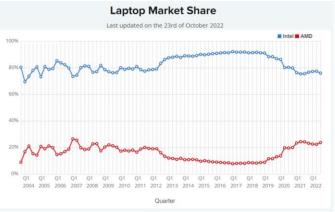




## >Porter's 5 Forces analysis









Even though AMD may have similar desktop market share, intel tend to keep lead in the CPU market





## >Porter's 5 Forces analysis

#### Threats of New Entrants

By innovating new products and services

By building economies of scale so that it can lower the fixed cost per unit

Building capacities and spending money on research and development

#### Bargaining Power of Buyers

By building a large base of customers

By rapidly innovating new products

New products will also reduce the defection of existing customers of Advanced Micro Devices, Inc. to its competitors

#### Rivalry among the Existing Competitors

By building a sustainable differentiation

By building scale so that it can compete better

Collaborating with competitors to increase the market size rather than just competing for small market.

#### **Bargaining Power of Suppliers**

By building efficient supply chain with multiple suppliers

Developing dedicated suppliers whose business depends upon the firm

By experimenting with product designs using different materials so that if the prices go up of one raw material then company can shift to another

#### Threats of Substitute Products or Services

By being service oriented rather than just product oriented

By understanding the core need of the customer rather than what the customer is buying

By increasing the switching cost for the customers







## >SWOT analysis

- High-Performance Computer
- 2. AMD Quality Policy
- 3. Key areas
- 4. Technology and Innovation
- 5. Global Operations
- 6. Strategic Sourcing
- 7. Outstanding research and Research and Development
- 8. With fewer competitors
- 9. Technologies
- 10. Achieving History
- 11. Guinness World Record Achievement

### **SWOT Analysis**

	Helpful to achieve objective	Harmful to achieve objective
Internal	Strengths	Weaknesses
External	Opportunities	Threats

Hivelr Business Journal

- 1. Lower Performance of the Computing Segment
- 2. The less seen in Mobile Market
- 3. Lower Market share
- 4. Quality Problems

Strengths:  Design Expertise  CPU power/performance  Graphics  Relatively nimble	Opportunities: Continue Taking CPU MSS GfX/CPU Integration Low Cost CPU for emerging markets
Weakness: High Debt / Low Cash History of Quality problems Manufacturing capacity Manufacturing process technology	Threats: Competing against much bigger and better funded market leader Continued price war Debt servicing will prevent R&D Cyclical Downturn

- 1. Rivals
- 2. Environmental Regulations
- 3. Rise in Raw Materials

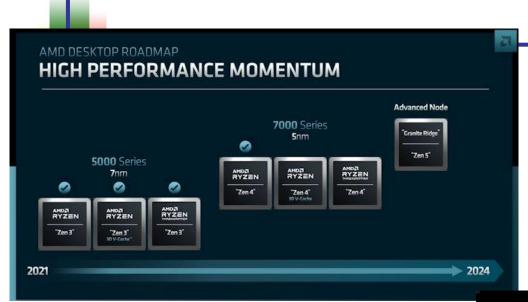


- 1. Permeate to Mobile
- 2. New product as well as Services
- 3. Virtualization Space4. Lost cost CPU
- 5. New Trends in Consumer Behavior



All gaming tests were with an RTX 2080 Ti





- ✓ Zen 5"-based "Granite Ridge" processors
- ✓ AMD's 3D V-Cache packaging technology will also come to client desktop Zen 4







AMD Ryzen 5 7600X vs AMD Ryzen 9 7950X vs Intel Core i5-13600K vs Intel Core i9-13900K [cpubenchmark.net] by PassMark Software

AMD Ryzen 3 1300X vs AMD Ryzen 7 5800X vs AMD Ryzen 9 5950X vs AMD Ryzen 7 7700X vs AMD Ryzen 9 7950X [cpubenchmark.net] by PassMark Software

AM5 vs. AM4: Worth The Upgrade? - Tech4Gamers

https://en.wikipedia.org/wiki/Ryzen

https://en.wikipedia.org/wiki/5\_nm\_process#cite\_note-41

https://www.anandtech.com/show/17585/amd-zen-4-ryzen-9-7950x-and-ryzen-5-7600x-review-retaking-the-high-end/6





# Thank you

